

4Mx16
SDRAM 52CSP
(VDD/VDDQ 3.0V/3.0V & 3.3V/3.3V)

Revision 0.6

November 2001

Revision History**Revision 0.0 (February 21, 2001, Target)**

- First generation of 64Mb Mobile SDRAM (VDD 3.0V, VDDQ 3.0V).

Revision 0.1 (April 21, 2001, Target)

- Addition of extended temperature(-25' C ~ 85' C) specification.
- Changed tRCD and tRP of -75 part from 22.5ns to 20ns, in order to cover 100MHz, 2-2-2 characteristics of 133MHz, 3-3-3 part.

Revision 0.2 (June 20, 2001, Target)

- Changed device name from low power sdram to mobile sdram.

Revision 0.3 (August 1, 2001, Preliminary)

- Integration to K4S641633F-GXXX of 3.0V and 3.3V part.
- Changed of tSAC from 6ns to 6.5ns in case of -1L part, from 7ns to 7.5ns in case of -15 part.
- Changed of tOH from 3ns to 2.5ns.
- Changed VIH min. from 2.0 V to 0.8xVDDQ and VOH min. from 2.4V to 0.9xVDDQ.

Revision 0.4 (October 10, 2001, Preliminary)

- Generation of -1H(100MHz, CL2) bin and deleting of -15(66MHz, CL2) bin.
- Changed of CL2 tSAC from 6ns to 7ns for -75 part, CL3 tSAC from 6ns to 7ns and CL2 tSAC from 6ns to 8ns and CL1 tSAC from 18ns to 20ns for -1L part.
- Changed of tOH from 3ns to 2.5ns.
- Changed of tSS from 2.5ns to 2.0ns for -75 part and from 3.0ns to 2.5ns for -1L part.
- Changed VIH min. from 0.8xVDDQ to 0.9xVDDQ and VOH min. from 0.9xVDDQ to 0.95xVDDQ.
- Changed IOH from -0.1mA to -2mA and IOL from 0.1mA to 2mA.
- Changed Commercial Temperature Range from 0 °C ~ 70°C to -25°C ~ 70°C.
- Changed Self Refresh Current.

Revision 0.5 (October 12, 2001, Preliminary)

- Changed VIH min. from 0.9xVDDQ to 2.0V and VOH min. from 0.95xVDDQ to 2.4V.
- Changed VIL max. from 0.3V to 0.8V and VOL min. from 0.2V to 0.4V.

Revision 0.6 (November 7, 2001, Preliminary)

- Changed VIH min. from 2.0V to 2.2V and VIL max. from 0.8V to 0.5V.

K4S641633F-GL(N)

1M x 16Bit x 4 Banks SDRAM in 52CSP

FEATURES

- 3.0V power supply.
- LVTTTL compatible with multiplexed address.
- Four banks operation.
- MRS cycle with address key programs.
 - CAS latency (1 & 2 & 3).
 - Burst length (1, 2, 4, 8 & Full page).
 - Burst type (Sequential & Interleave).
- EMRS cycle with address key programs.
- All inputs are sampled at the positive going edge of the system clock.
- Burst read single-bit write operation.
- DQM for masking.
- Auto refresh.
- 64ms refresh period (4K cycle).
- Commercial Temperature Operation (-25°C ~ 70°C).
Extended Temperature Operation (-25°C ~ 85°C).
- 52Balls CSP.

GENERAL DESCRIPTION

The K4S641633F is 67,108,864 bits synchronous high data rate Dynamic RAM organized as 4 x 1,048,576 words by 16 bits, fabricated with SAMSUNG's high performance CMOS technology. Synchronous design allows precise cycle control with the use of system clock I/O transactions are possible on every clock cycle. Range of operating frequencies, programmable burst length and programmable latencies allow the same device to be useful for a variety of high bandwidth, high performance memory system applications.

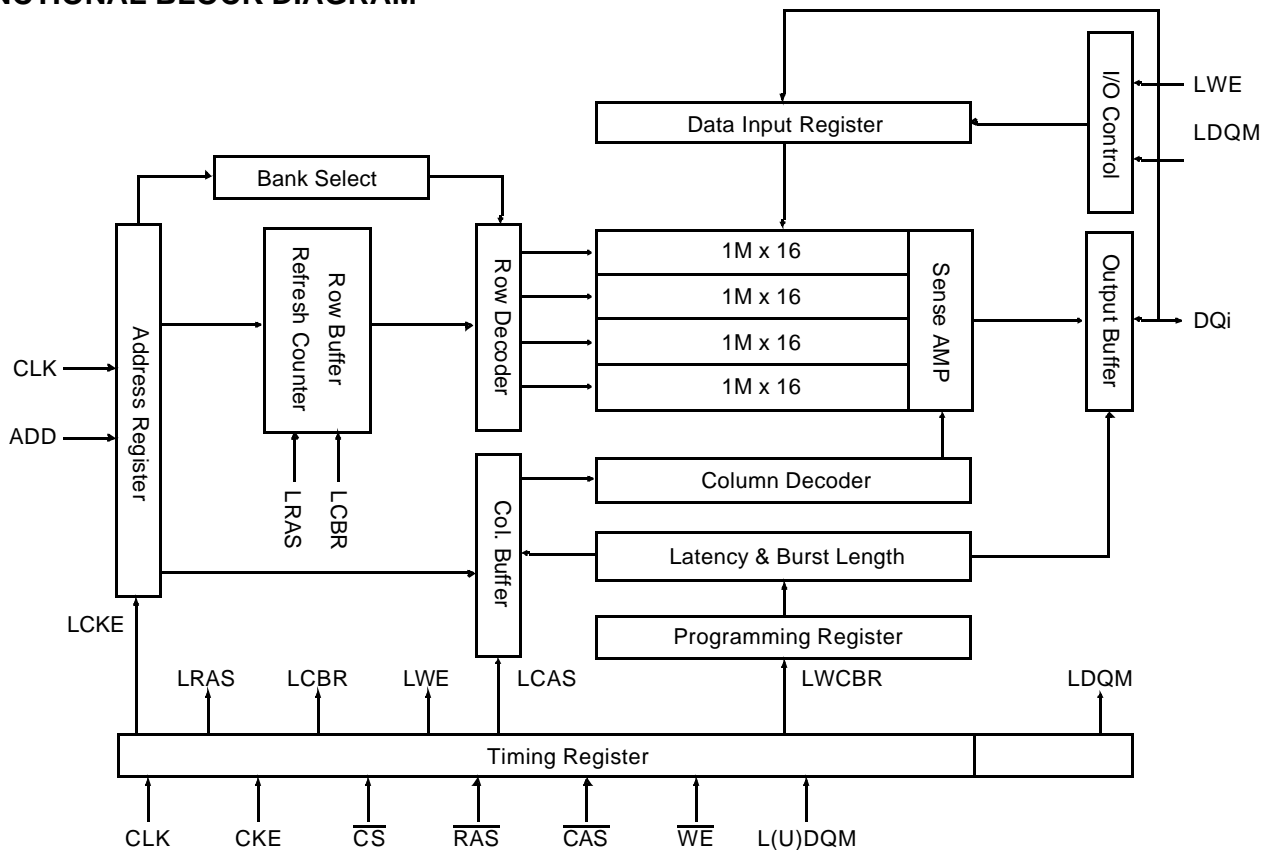
ORDERING INFORMATION

Part No.	Max Freq.	Interface	Package
K4S641633F-GL/N75	133MHz(CL=3) 100MHz(CL=2)	LVTTTL	52 CSP
K4S641633F-GL/N1H	100MHz(CL=2)		
K4S641633F-GL/N1L	100MHz(CL=3) ^{*1}		

-GL ; Low Power, Operating Temperature ; -25°C ~ 70°C.
-GN ; Low Power, Operating Temperature ; -25°C ~ 85°C.

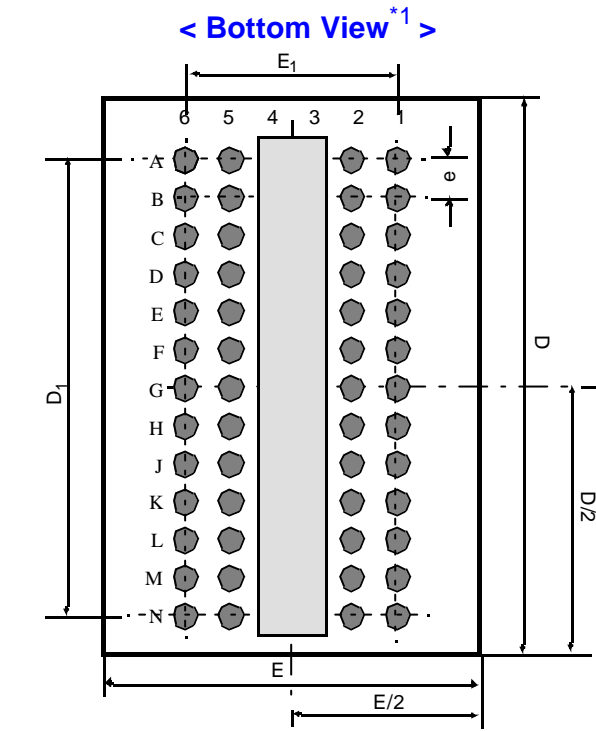
Note :1. In case of 40MHz Frequency, CL1 can be supported.

FUNCTIONAL BLOCK DIAGRAM



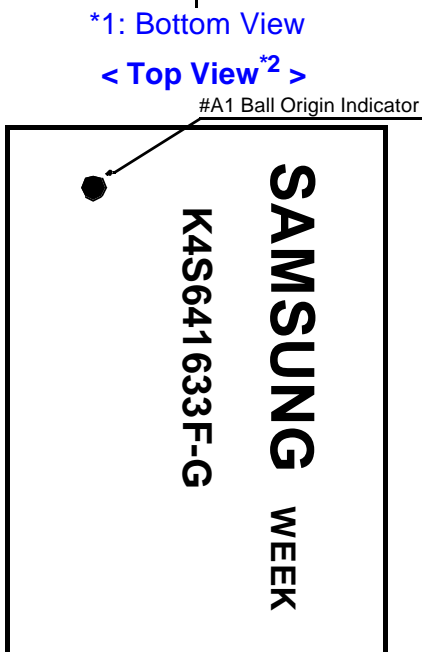
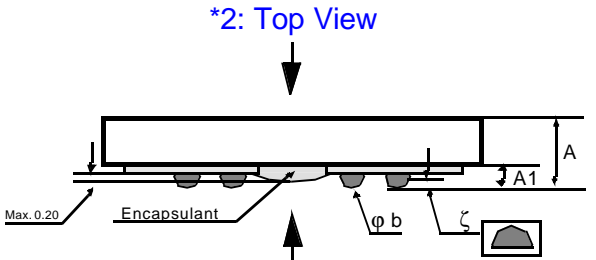
* Samsung Electronics reserves the right to change products or specification without notice.

Package Dimension and Pin Configuration



< Top View *2 >

52Ball(4x13) CSP				
	1	2	5	6
A	V _{SS}	DQ15	DQ0	V _{DD}
B	DQ14	V _{SSQ}	V _{DDQ}	DQ1
C	DQ13	V _{DDQ}	V _{SSQ}	DQ2
D	DQ12	DQ11	DQ4	DQ3
E	DQ10	V _{SSQ}	V _{DDQ}	DQ5
F	DQ9	V _{DDQ}	V _{SSQ}	DQ6
G	DQ8	V _{DD}	V _{SS}	DQ7
H	CLK	UDQM	LDQM	\overline{WE}
J	CKE	\overline{CS}	\overline{RAS}	\overline{CAS}
K	A11	A9	BA1	BA0
L	A8	A7	A0	A10
M	A6	A5	A2	A1
N	V _{SS}	A4	A3	V _{DD}



Pin Name	Pin Function
CLK	System Clock
\overline{CS}	Chip Select
CKE	Clock Enable
A ₀ ~ A ₁₁	Address
BA ₀ ~ BA ₁	Bank Select Address
\overline{RAS}	Row Address Strobe
\overline{CAS}	Column Address Strobe
\overline{WE}	Write Enable
L(U)DQM	Data Input/Output Mask
DQ ₀ ~ 15	Data Input/Output
V _{DD} /V _{SS}	Power Supply/Ground
V _{DDQ} /V _{SSQ}	Data Output Power/Ground

[Unit:mm]

Symbol	Min	Typ	Max
A	0.90	0.95	1.00
A ₁	-	0.35	-
E	-	6.60	-
E ₁	-	3.75	-
D	-	11.00	-
D ₁	-	9.0	-
e	-	0.75	-
b	0.40	0.45	0.5
ζ	-	-	0.08

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Voltage on any pin relative to Vss	V _{IN} , V _{OUT}	-1.0 ~ 4.6	V
Voltage on V _{DD} supply relative to Vss	V _{DD} , V _{DDQ}	-1.0 ~ 4.6	V
Storage temperature	T _{STG}	-55 ~ +150	°C
Power dissipation	P _D	1	W
Short circuit current	I _{OS}	50	mA

Note : Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded.
Functional operation should be restricted to recommended operating condition.
Exposure to higher than recommended voltage for extended periods of time could affect device reliability.

DC OPERATING CONDITIONS

Recommended operating conditions (Voltage referenced to Vss = 0V, T_A = -25°C ~ 70°C (Commercial), -25°C ~ 85°C (Extended))

Parameter	Symbol	Min	Typ	Max	Unit	Note
Supply voltage	V _{DD}	2.7	3.0	3.6	V	
	V _{DDQ}	2.7	3.0	3.6	V	
Input logic high voltage	V _{IH}	2.2	3.0	V _{DDQ} +0.3	V	1
Input logic low voltage	V _{IL}	-0.3	0	0.5	V	2
Output logic high voltage	V _{OH}	2.4	-	-	V	I _{OH} = -2mA
Output logic low voltage	V _{OL}	-	-	0.4	V	I _{OL} = 2mA
Input leakage current	I _{LI}	-10	-	10	uA	3

Note : 1. V_{IH} (max) = 5.3V AC. The overshoot voltage duration is ≤ 3ns.
2. V_{IL} (min) = -2.0V AC. The undershoot voltage duration is ≤ 3ns.
3. Any input 0V ≤ V_{IN} ≤ V_{DDQ}.
Input leakage currents include HI-Z output leakage for all bi-directional buffers with Tri-State outputs.
4. Dout is disabled, 0V ≤ V_{OUT} ≤ V_{DDQ}.

CAPACITANCE (V_{DD} = 3.0V, T_A = 23°C, f = 1MHz, V_{REF} = 0.9V ± 50 mV)

Pin	Symbol	Min	Max	Unit	Note
Clock	C _{CLK}	2.0	4.0	pF	
$\overline{\text{RAS}}$, $\overline{\text{CAS}}$, $\overline{\text{WE}}$, $\overline{\text{CS}}$, CKE, DQM	C _{IN}	2.0	4.0	pF	
Address	C _{ADD}	2.0	4.0	pF	
DQ ₀ ~ DQ ₁₅	C _{OUT}	3.5	6.0	pF	

DC CHARACTERISTICS

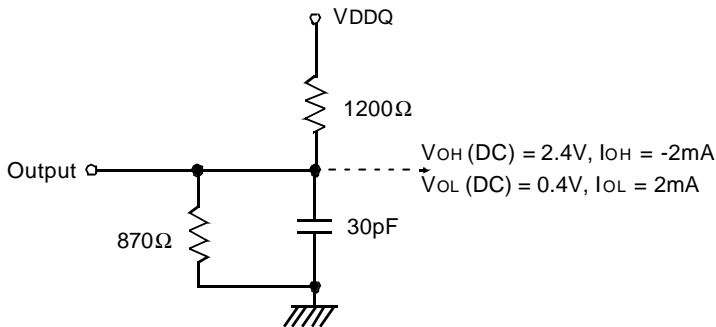
Recommended operating conditions (Voltage referenced to $V_{SS} = 0V$, $T_A = -25^\circ C \sim 70^\circ C$ (Commercial), $-25^\circ C \sim 85^\circ C$ (Extended))

Parameter	Symbol	Test Condition	Version			Unit	Note
			-75	-1H	-1L		
Operating Current (One Bank Active)	I_{CC1}	Burst length = 1 $t_{RC} \geq t_{RC}(\min)$ $I_o = 0 \text{ mA}$	60	55	55	mA	1
Precharge Standby Current in power-down mode	I_{CC2P}	$CKE \leq V_{IL}(\max)$, $t_{CC} = 10\text{ns}$	0.5			mA	
	I_{CC2PS}	$CKE \ \& \ CLK \leq V_{IL}(\max)$, $t_{CC} = \infty$	0.5				
Precharge Standby Current in non power-down mode	I_{CC2N}	$CKE \geq V_{IH}(\min)$, $\overline{CS} \geq V_{IH}(\min)$, $t_{CC} = 10\text{ns}$ Input signals are changed one time during 20ns	11			mA	
	I_{CC2NS}	$CKE \geq V_{IH}(\min)$, $CLK \leq V_{IL}(\max)$, $t_{CC} = \infty$ Input signals are stable	8				
Active Standby Current in power-down mode	I_{CC3P}	$CKE \leq V_{IL}(\max)$, $t_{CC} = 10\text{ns}$	5			mA	
	I_{CC3PS}	$CKE \ \& \ CLK \leq V_{IL}(\max)$, $t_{CC} = \infty$	5				
Active Standby Current in non power-down mode (One Bank Active)	I_{CC3N}	$CKE \geq V_{IH}(\min)$, $\overline{CS} \geq V_{IH}(\min)$, $t_{CC} = 10\text{ns}$ Input signals are changed one time during 20ns	22			mA	
	I_{CC3NS}	$CKE \geq V_{IH}(\min)$, $CLK \leq V_{IL}(\max)$, $t_{CC} = \infty$ Input signals are stable	22				
Operating Current (Burst Mode)	I_{CC4}	$I_o = 0 \text{ mA}$ Page burst 4Banks Activated $t_{CCD} = 2CLKs$	90	70	70	mA	1
Refresh Current	I_{CC5}	$t_{RC} \geq t_{RC}(\min)$	135	120	120	mA	2
Self Refresh Current	I_{CC6}	$CKE \leq 0.2V$	-GL	400		uA	3
			-GN			uA	4

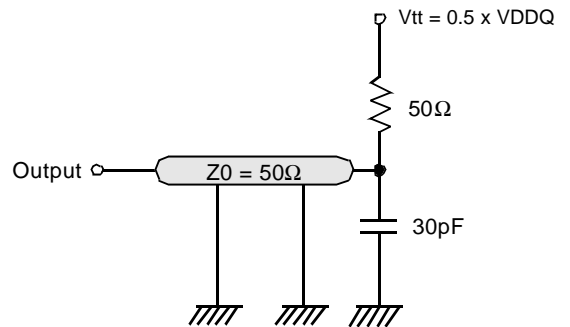
- Notes :**
1. Measured with outputs open.
 2. Refresh period is 64ms.
 3. K4S641633F-GL**
 4. K4S641633F-GN**
 5. Unless otherwise noted, input swing level is CMOS($V_{IH}/V_{IL}=V_{DDQ}/V_{SSQ}$)

AC OPERATING TEST CONDITIONS ($V_{DD} = 2.7V \sim 3.6V$, $T_A = -25^\circ C \sim 70^\circ C$ (Commercial), $-25^\circ C \sim 85^\circ C$ (Extended))

Parameter	Value	Unit
AC input levels (V_{ih}/V_{il})	2.4 / 0.4	V
Input timing measurement reference level	$0.5 \times V_{DDQ}$	V
Input rise and fall time	$t_r/t_f = 1/1$	ns
Output timing measurement reference level	$0.5 \times V_{DDQ}$	V
Output load condition	See Fig. 2	



(Fig. 1) DC output load circuit



(Fig. 2) AC output load circuit

OPERATING AC PARAMETER

(AC operating conditions unless otherwise noted)

Parameter	Symbol	Version			Unit	Note
		- 75	-1H	-1L		
Row active to row active delay	$t_{RRD}(\min)$	15	20	20	ns	1
RAS to CAS delay	$t_{RCD}(\min)$	20	20	24	ns	1
Row precharge time	$t_{RP}(\min)$	20	20	24	ns	1
Row active time	$t_{RAS}(\min)$	45	50	60	ns	1
	$t_{RAS}(\max)$	100			us	
Row cycle time	$t_{RC}(\min)$	65	70	84	ns	1
Last data in to row precharge	$t_{RD}(\min)$	2			CLK	2
Last data in to Active delay	$t_{DAL}(\min)$	2 CLK + t_{RP}			-	
Last data in to new col. address delay	$t_{CDL}(\min)$	1			CLK	2
Last data in to burst stop	$t_{BDL}(\min)$	1			CLK	2
Col. address to col. address delay	$t_{CCD}(\min)$	1			CLK	3
Number of valid output data	CAS latency=3	2			ea	4
	CAS latency=2	1				
	CAS latency=1	-	0			

- Notes :**
1. The minimum number of clock cycles is determined by dividing the minimum time required with clock cycle time and then rounding off to the next higher integer.
 2. Minimum delay is required to complete write.
 3. All parts allow every cycle column address change.
 4. In case of row precharge interrupt, auto precharge and read burst stop.

AC CHARACTERISTICS (AC operating conditions unless otherwise noted)

Parameter		Symbol	- 75		-1H		-1L		Unit	Note
			Min	Max	Min	Max	Min	Max		
CLK cycle time	CAS latency=3	tcc	7.5	1000	10	1000	10	1000	ns	1
	CAS latency=2		10		10		12			
	CAS latency=1		-		-		25			
CLK to valid output delay	CAS latency=3	tsac		5.4		7		7	ns	1,2
	CAS latency=2			7		7		8		
	CAS latency=1			-		-		20		
Output data hold time	CAS latency=3	toH	2.5		2.5		2.5		ns	2
	CAS latency=2		2.5		2.5		2.5			
	CAS latency=1		-		-		2.5			
CLK high pulse width		tCH	2.5		3		3		ns	3
CLK low pulse width		tCL	2.5		3		3		ns	3
Input setup time		tSS	2.0		2.5		2.5		ns	3
Input hold time		tSH	1.0		1.5		1.5		ns	3
CLK to output in Low-Z		tSLZ	1		1		1		ns	2
CLK to output in Hi-Z	CAS latency=3	tSHZ		5.4		7		7	ns	
	CAS latency=2			7		7		8		
	CAS latency=1			-		-		20		

- Notes :**
- Parameters depend on programmed CAS latency.
 - If clock rising time is longer than 1ns, $(tr/2-0.5)ns$ should be added to the parameter.
 - Assumed input rise and fall time (tr & tf) = 1ns.
If tr & tf is longer than 1ns, transient time compensation should be considered,
i.e., $[(tr + tf)/2-1]ns$ should be added to the parameter.

SIMPLIFIED TRUTH TABLE

COMMAND		CKEn-1	CKEn	\overline{CS}	\overline{RAS}	\overline{CAS}	\overline{WE}	DQM	BA _{0,1}	A _{10/AP}	A ₁₁ , A _{9 ~ A₀}	Note	
Register	Mode Register Set	H	X	L	L	L	L	X	OP CODE			1, 2	
Refresh	Auto Refresh	H	H	L	L	L	H	X	X			3	
	Entry		L									3	
	Self Refresh	Exit	L	H	L	H	H	H	X	X			3
					H	X	X	X					3
Bank Active & Row Addr.		H	X	L	L	H	H	X	V	Row Address			
Read & Column Address	Auto Precharge Disable	H	X	L	H	L	H	X	V	L	Column Address (A ₀ ~A ₇)		4
	Auto Precharge Enable									H			4, 5
Write & Column Address	Auto Precharge Disable	H	X	L	H	L	L	X	V	L	Column Address (A ₀ ~A ₇)		4
	Auto Precharge Enable									H			4, 5
Burst Stop		H	X	L	H	H	L	X	X			6	
Precharge	Bank Selection	H	X	L	L	H	L	X	V	L	X		
	All Banks								X	H			
Clock Suspend or Active Power Down	Entry	H	L	H	X	X	X	X	X				
				L	V	V	V						
Precharge Power Down Mode	Entry	H	L	H	X	X	X	X	X				
				L	H	H	H						
	Exit	L	H	H	X	X	X	X	X				
				L	V	V	V						
DQM		H	X					V	X			7	
No Operation Command		H	X	H	X	X	X	X	X				
L	H			H	H								

(V=Valid, X=Don't Care, H=Logic High, L=Logic Low)

Note : 1. OP Code : Operand Code

A₀ ~ A₁₁ & BA₀ ~ BA₁ : Program keys. (@MRS)

2. MRS can be issued only at all banks precharge state.

A new command can be issued after 2 CLK cycles of MRS.

3. Auto refresh functions are as same as CBR refresh of DRAM.

The automatical precharge without row precharge command is meant by "Auto".

Auto/self refresh can be issued only at all banks precharge state.

4. BA₀ ~ BA₁ : Bank select addresses.

If both BA₀ and BA₁ are "Low" at read, write, row active and precharge, bank A is selected.

If both BA₀ is "Low" and BA₁ is "High" at read, write, row active and precharge, bank B is selected.

If both BA₀ is "High" and BA₁ is "Low" at read, write, row active and precharge, bank C is selected.

If both BA₀ and BA₁ are "High" at read, write, row active and precharge, bank D is selected.

If A_{10/AP} is "High" at row precharge, BA₀ and BA₁ is ignored and all banks are selected.

5. During burst read or write with auto precharge, new read/write command can not be issued.

Another bank read/write command can be issued after the end of burst.

New row active of the associated bank can be issued at t_{RP} after the end of burst.

6. Burst stop command is valid at every burst length.

7. DQM sampled at positive going edge of a CLK and masks the data-in at the very CLK (Write DQM latency is 0), but makes Hi-Z state the data-out of 2 CLK cycles after. (Read DQM latency is 2)

MODE REGISTER FIELD TABLE TO PROGRAM MODES

Register Programmed with Normal MRS

Address	BA0 ~ BA1*1	A11 ~ A10/AP	A9	A8	A7	A6	A5	A4	A3	A2	A1	A0
Function	"0" Setting for Normal MRS	RFU	W.B.L	Test Mode		CAS Latency			BT	Burst Length		

Normal MRS Mode

Test Mode			CAS Latency				Burst Type			Burst Length				
A8	A7	Type	A6	A5	A4	Latency	A3	Type		A2	A1	A0	BT=0	BT=1
0	0	Mode Register Set	0	0	0	Reserved	0	Sequential		0	0	0	1	1
0	1	Reserved	0	0	1	1	1	Interleave		0	0	1	2	2
1	0	Reserved	0	1	0	2	Mode Select			0	1	0	4	4
1	1	Reserved	0	1	1	3	BA1	BA0	Mode	0	1	1	8	8
Write Burst Length			1	0	0	Reserved	0	0	Setting for Normal MRS	1	0	0	Reserved	Reserved
A9	Length		1	0	1	Reserved				1	0	1	Reserved	Reserved
0	Burst		1	1	0	Reserved				1	1	0	Reserved	Reserved
1	Single Bit		1	1	1	Reserved				1	1	1	Full Page	Reserved

Full Page Length : 256(x16)

Power Up Sequence

1. Apply power and start clock, Attempt to maintain CKE= "H", DQM= "H" and the other pins are NOP condition at the inputs.
2. Power is applied to VDD and VDDQ (simultaneously).
3. Maintain stable power, stable clock and NOP input condition for a minimum of 200us.
4. Issue precharge commands for all banks of the devices.
5. Issue 2 or more auto-refresh commands.
6. Issue a mode register set command to initialize the mode register.

Note : 1. In order to assert normal MRS, BA0 and BA1 should set "0" absolutely.